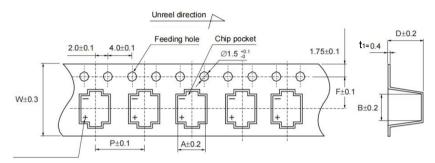


• SMD Type Taping Specifications

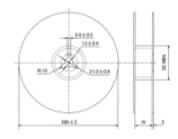
• Carrier Tape Dimensions





-							unit: mm
Case size	W	Α	В	Р	F	t ₁	D
Case size	±0.3	±0.2	±0.2	±0.1	±0.1	±0.1	±0.2
6.3 x 6.0	16.0	7.0	7.0	12.0	7.5	0.4	6.4
6.3 x 7.7	16.0	7.0	7.0	12.0	7.5	0.4	8.4
8 x 10	24.0	8.7	8.7	16.0	11.5	0.4	11.0
8 x 12.5	24.0	8.7	8.7	16.0	11.5	0.4	13.2
10 x 10.5	24.0	10.7	10.7	16.0	11.5	0.4	11.0
10 x 12.8	24.0	10.7	10.7	16.0	11.5	0.4	13.2
10 x 16.5	24.0	10.7	10.7	16.0	11.5	0.4	17.5

• Packaging Specifications



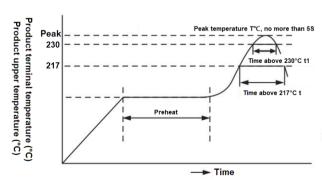
Case size	W	Pool (pcc)	Carton (ncc)	Code
Case size	mm	Reel (pcs)	Carton (pcs)	
6.3 x 6.0	18	1,000	10,000	
6.3 x 7.7	18	1,000	10,000	
8 x 10	26	500	3,500	
8 x 12.5	26	500	3,500	TR
10 x 12.5	26	500	3,500	
10 x 12.8	26	500	3,500	

• Lead Free Type Reflow Soldering Condition

- Size Ø 6.3~Ø 10
- 1) Temperature at surface of capacitor shall not exceed T°C.
- 2) Period that temperature at the surface of capacitor becomes more than 200°C and soldering shall not exceed t and t₁ seconds.
- 3) Preheat shall be made at 100°C ~ 180°C and for maximum 120 seconds.
- 4) Please ensure that the capacitor became cold enough to the room temperature before the second reflow.

	T℃	t₁ ≥ 230°C	t ≥ 217°C	≥ 200°C	Reflow times
Ø6.3	260	30	40	70	2
Ø8~10	260	30	40	70	1
Ø8~10	245	30	40	70	2

- ① T°C: Peak temperature
- $\ensuremath{@}$ Time more than 200 $\ensuremath{^{\circ}}$
- * Please contact us if the condition is over the maximum.



Recommended Land Size Case size Ø 6.3 Ø 8 Ø 10 Solder Land

			unit: mm
Case size	х	у	а
ø 6.3	1.6	3.5	2.1
ø 8	2.0	3.5	3.0
ø 10	2.0	4.0	4.0
Ø 10	2.0	4.0	4.0

• Radial lead type:

Recommended soldering heat conditions

Preheat: 150°C 120 seconds Max. Flow soldering: 260 +5°C Max. 10+1 seconds Max.